



SILEGO

SLG7NT41563

Fog Project

FOR INTERNAL USE ONLY

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Internal Use Only



General Description

Silego SLG7NT41563 is a low power and small form device. The SoC is housed in a 2mm x 3mm STQFN package which is optimal for using with small devices.

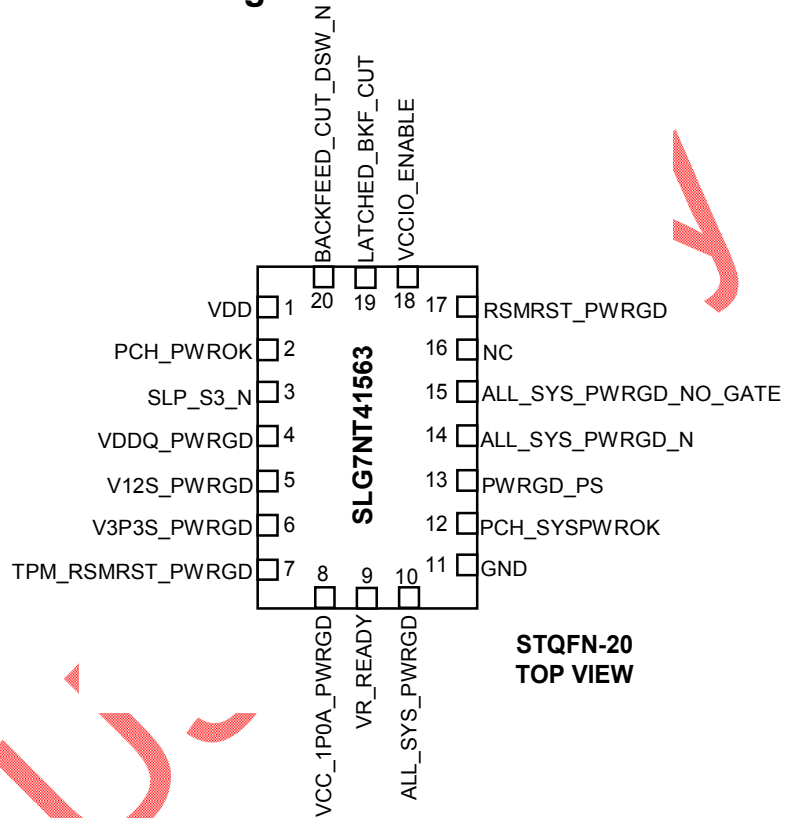
Features

- Low Power Consumption
- Pb-Free / RoHS Compliant
- Halogen-Free
- STQFN-20 Package

Output Summary

- 2 Outputs — Push Pull 1X
- 2 Outputs — Push Pull 2X
- 4 Outputs — Open Drain NMOS 2X

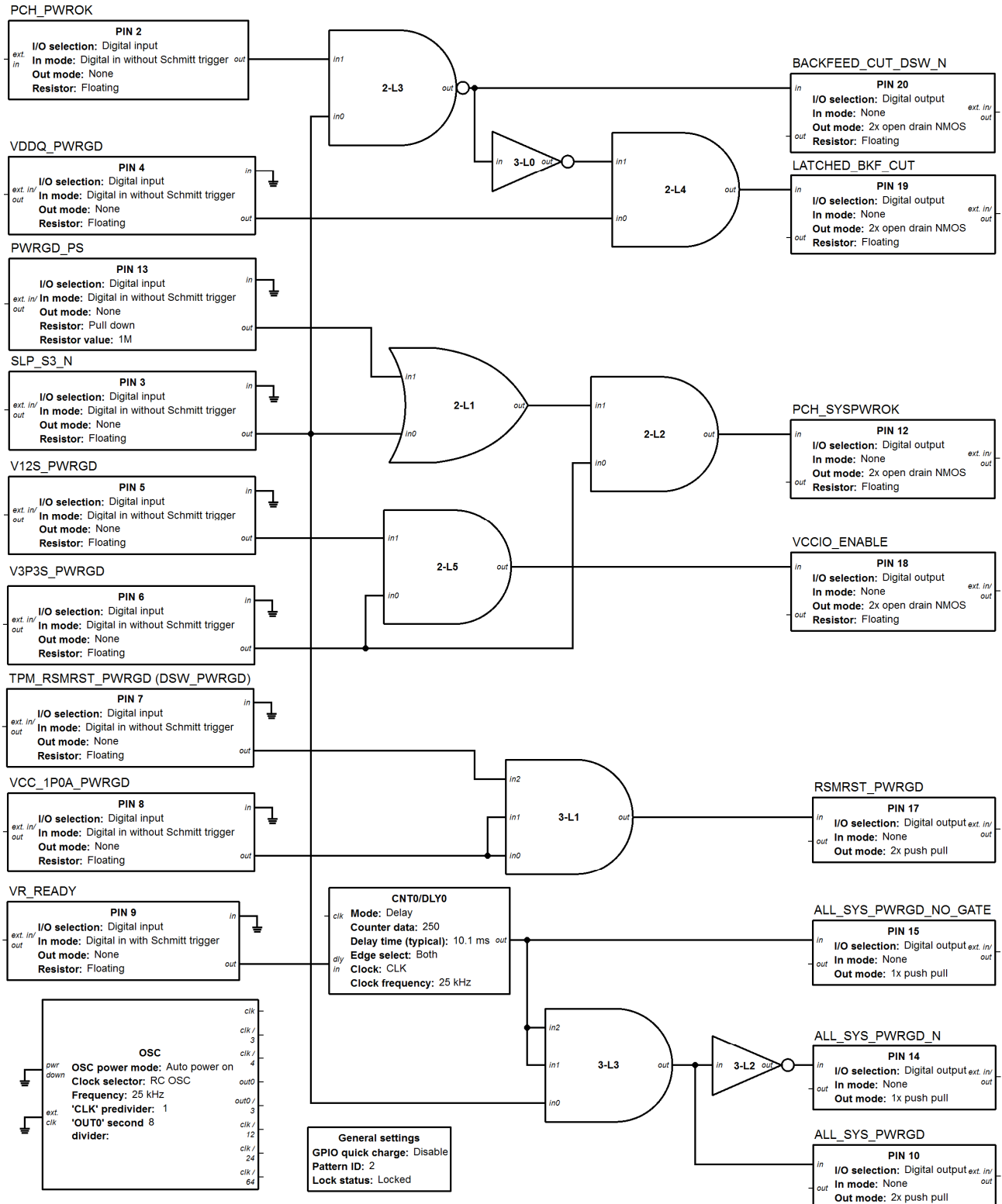
Pin Configuration



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Block Diagram





Pin Configuration

Pin #	Pin Name	Type	Pin Description
1	VDD	PWR	Supply Voltage
2	PCH_PWROK	Digital Input	Digital Input without Schmitt trigger
3	SLP_S3_N	Digital Input	Digital Input without Schmitt trigger
4	VDDQ_PWRGD	Digital Input	Digital Input without Schmitt trigger
5	V12S_PWRGD	Digital Input	Digital Input without Schmitt trigger
6	V3P3S_PWRGD	Digital Input	Digital Input without Schmitt trigger
7	TPM_RSMRST_PWRGD	Digital Input	Digital Input without Schmitt trigger
8	VCC_1P0A_PWRGD	Digital Input	Digital Input without Schmitt trigger
9	VR_READY	Digital Input	Digital Input with Schmitt trigger
10	ALL_SYS_PWRGD	Digital Output	Push Pull 2X
11	GND	GND	Ground
12	PCH_SYSPWROK	Digital Output	Open Drain NMOS 2X
13	PWRGD_PS	Digital Input	Digital Input without Schmitt trigger
14	ALL_SYS_PWRGD_N	Digital Output	Push Pull 1X
15	ALL_SYS_PWRGD_NO_GATE	Digital Output	Push Pull 1X
16	NC	--	Keep Floating or Connect to GND
17	RSMRST_PWRGD	Digital Output	Push Pull 2X
18	VCCIO_ENABLE	Digital Output	Open Drain NMOS 2X
19	LATCHED_BKF_CUT	Digital Output	Open Drain NMOS 2X
20	BACKFEED_CUT_DSW_N	Digital Output	Open Drain NMOS 2X

Ordering Information

Part Number	Package Type
SLG7NT41563V	V=STQFN-20
SLG7NT41563VTR	VTR=STQFN-20 – Tape and Reel (3k units)



Absolute Maximum Conditions

Parameter	Min.	Max.	Unit
V _{HIGH} to GND	-0.3	7	V
Voltage at input pins	-0.3	7	V
Current at input pin	-1.0	1.0	mA
Storage temperature range	-65	125	°C
Junction temperature	--	150	°C
ESD Protection (Human Body Model)	2000	--	V
ESD Protection (Charged Device Model)	1300	--	V
Moisture Sensitivity Level	1		

Electrical Characteristics

(@ 25°C, unless otherwise stated)

Symbol	Parameter	Condition/Note	Min.	Typ.	Max.	Unit
V _{DD}	Supply Voltage		1.71	3.3	5.5	V
T _A	Operating Temperature		-40	25	85	°C
I _Q	Quiescent Current	Static inputs and outputs	--	1	--	µA
V _O	Maximal Voltage Applied to any PIN in High-Impedance State		--	--	VDD	V
I _O	Maximal Average or DC Current (note 1)	Per Each Chip Side (PIN2-PIN10, PIN12-PIN20)	--	--	90	mA
V _{IH}	HIGH-Level Input Voltage	Logic Input, at VDD=1.8V	1.10	--	VDD	V
		Logic Input with Schmitt Trigger, at VDD=1.8V	1.27	--	VDD	
		Logic Input, at VDD=3.3V	1.78	--	VDD	
		Logic Input with Schmitt Trigger, at VDD=3.3V	2.13	--	VDD	
		Logic Input, at VDD=5.0V	2.64	--	VDD	
		Logic Input with Schmitt Trigger, at VDD=5.0V	3.16	--	VDD	
V _{IL}	LOW-Level Input Voltage	Logic Input, at VDD=1.8V	--	--	0.69	V
		Logic Input with Schmitt Trigger, at VDD=1.8V	--	--	0.44	
		Logic Input, at VDD=3.3V	--	--	1.21	
		Logic Input with Schmitt Trigger, at VDD=3.3V	--	--	0.95	
		Logic Input, at VDD=5.0V	--	--	1.84	
		Logic Input with Schmitt Trigger, at VDD=5.0V	--	--	1.51	
I _{IH}	HIGH-Level Input Current	Logic Input PINs; V _{IN} = VDD	-1.0	--	1.0	µA
I _{IL}	LOW-Level Input Current	Logic Input PINs; V _{IN} = 0V	-1.0	--	1.0	µA
V _{OH}	HIGH-Level Output Voltage	Push Pull & PMOS OD, I _{OH} = 100µA, 1X Driver, at VDD=1.8 V	1.69	1.789	--	V



		Push Pull & PMOS OD, $I_{OH} = 100\mu A$, 2X Driver, at VDD=1.8 V	1.7	1.794	--	
		Push Pull & PMOS OD, $I_{OH} = 3mA$, 1X Driver, at VDD=3.3 V	2.735	3.12	--	
		Push Pull & PMOS OD, $I_{OH} = 3mA$, 2X Driver, at VDD=3.3 V	2.87	3.21	--	
		Push Pull & PMOS OD, $I_{OH} = 5mA$, 1X Driver, at VDD=5.0 V	4.19	4.78	--	
		Push Pull & PMOS OD, $I_{OH} = 5mA$, 2X Driver, at VDD=5.0 V	4.32	4.89	--	
V_{OL}	LOW-Level Output Voltage	Push Pull, $I_{OL} = 100\mu A$, 1X Driver, at VDD=1.8 V	--	0.008	0.03	V
		Push Pull, $I_{OL} = 100\mu A$, 2X Driver, at VDD=1.8 V	--	0.004	0.01	
		Open Drain, $I_{OL} = 100\mu A$, 2X Driver, at VDD=1.8 V	--	0.003	0.01	
		Push Pull, $I_{OL} = 3mA$, 1X Driver, at VDD=3.3 V	--	0.13	0.228	
		Push Pull, $I_{OL} = 3mA$, 2X Driver, at VDD=3.3 V	--	0.060	0.108	
		Open Drain, $I_{OL} = 3mA$, 2X Driver, at VDD=3.3 V	--	0.04	0.08	
		Push Pull, $I_{OL} = 5mA$, 1X Driver, at VDD=5.0 V	--	0.157	0.270	
		Push Pull, $I_{OL} = 5mA$, 2X Driver, at VDD=5.0 V	--	0.076	0.140	
		Open Drain, $I_{OL} = 5mA$, 2X Driver, at VDD=5.0 V	--	0.051	0.11	
I_{OH}	HIGH-Level Output Current	Push Pull & PMOS OD, $V_{OH} = V_{DD}-0.2$, 1X Driver, at VDD=1.8 V	1.066	1.703	--	mA
		Push Pull & PMOS OD, $V_{OH} = V_{DD}-0.2$, 2X Driver, at VDD=1.8 V	2.216	3.406	--	
		Push Pull & PMOS OD, $V_{OH} = 2.4 V$, 1X Driver, at VDD=3.3 V	6.045	12.08	--	
		Push Pull & PMOS OD, $V_{OH} = 2.4 V$, 2X Driver, at VDD=3.3 V	11.522	24.16	--	
		Push Pull & PMOS OD, $V_{OH} = 2.4 V$, 1X Driver, at VDD=5.0 V	22.08	34.04	--	
		Push Pull & PMOS OD, $V_{OH} = 2.4 V$, 2X Driver, at VDD=5.0 V	41.69	68.08	--	
I_{OL}	LOW-Level Output Current	Push Pull, $V_{OL} = 0.15V$, 1X Driver, at VDD=1.8 V	0.917	1.689	--	mA
		Push Pull, $V_{OL} = 0.15V$, 2X Driver, at VDD=1.8 V	1.834	3.378	--	
		Open Drain, $V_{OL} = 0.15V$, 2X Driver, at VDD=1.8 V	2.750	5.068	--	
		Push Pull, $V_{OL} = 0.4V$, 1X Driver, at VDD=3.3 V	4.875	8.244	--	
		Push Pull, $V_{OL} = 0.4V$, 2X Driver, at VDD=3.3 V	9.750	16.488	--	
		Open Drain, $V_{OL} = 0.4V$, 2X Driver, at VDD=3.3 V	14.541	24.74	--	



		Push Pull, $V_{OL}=0.4V$, 1X Driver, at $V_{DD}=5.0V$	7.215	11.58	--	
		Push Pull, $V_{OL}=0.4V$, 2X Driver, at $V_{DD}=5.0V$	13.831	23.16	--	
		Open Drain, $V_{OL}=0.4V$, 2X Driver, at $V_{DD}=5.0V$	17.343	34.76	--	
R_{PULL_DOWN}	Internal Pull Down Resistance	Pull down on PIN 13	700	1000	1300	k Ω
T_{DLY0}	Delay0 Time	At temperature 25°C	9.09	10.1	10.6	ms
		At temperature -40°C +85°C (note 1)	8.24	10.1	12.55	ms
T_{SU}	Start up Time	From VDD rising past 1.35V	--	0.3	--	ms

1. Guaranteed by Design.

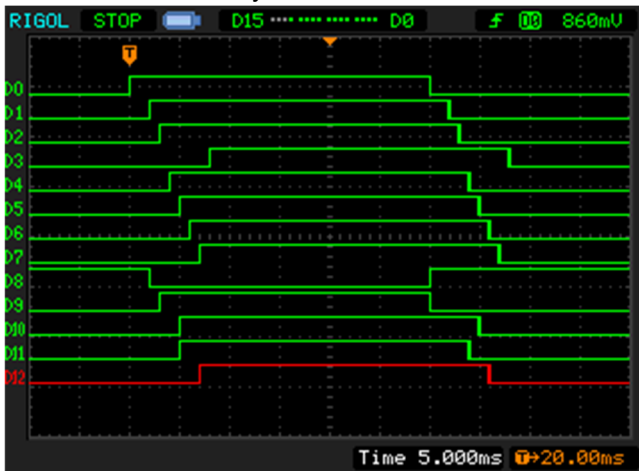
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Functionality Waveforms

- D0 – PIN#2 (PCH_PWROK)
- D1 – PIN#3 (SLP_S3_N)
- D2 – PIN#4 (VDDQ_PWRGD)
- D3 – PIN#13 (PWRGD_PS)
- D4 – PIN#5 (V12S_PWRGD)
- D5 – PIN#6 (V3P3S_PWRGD)
- D6 – PIN#7 (TPM_RSMRST_PWRGD)
- D7 – PIN#8 (VCC_1P0A_PWRGD)
- D8 – PIN#20 (BACKFEED_CUT_DSW_N) with external 5kΩ pull up resistor
- D9 – PIN#19 (LATCHED_BKF_CUT) with external 5kΩ pull up resistor
- D10 – PIN#12 (PCH_SYSPWROK) with external 5kΩ pull up resistor
- D11 – PIN#18 (VCCIO_ENABLE) with external 5kΩ pull up resistor
- D12 – PIN#17 (RSMRST_PWRGD)

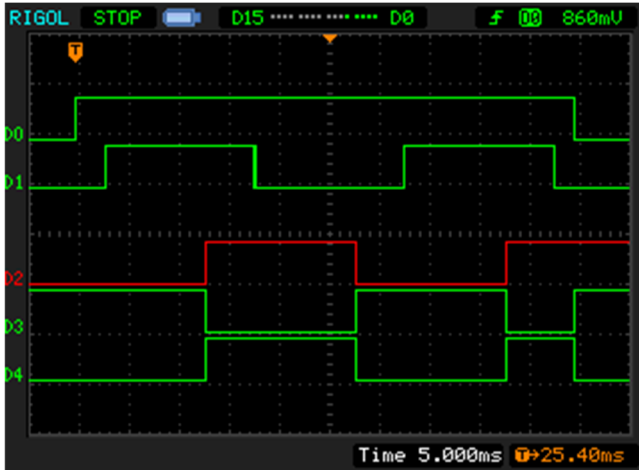
1. Device functionality





- D0 – PIN#3 (SLP_S3_N)
- D1 – PIN#9 (VR_READY)
- D2 – PIN#15 (ALL_SYS_PWRGD_NO_GATE)
- D3 – PIN#14 (ALL_SYS_PWRGD_N)
- D4 – PIN#10 (ALL_SYS_PWRGD)

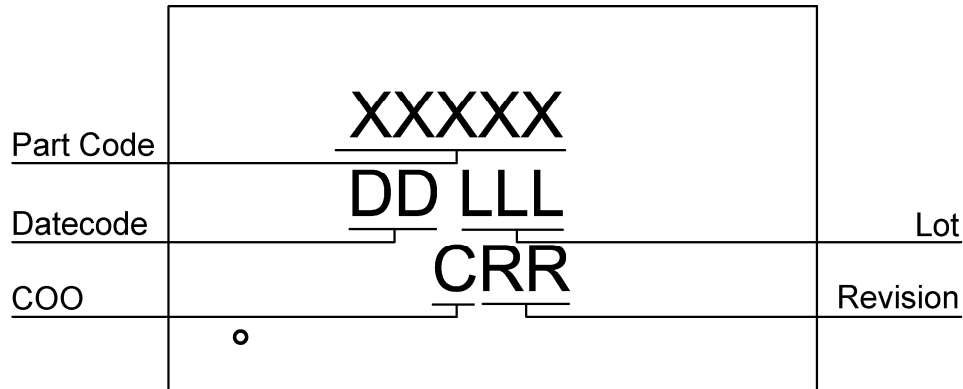
2. Device functionality



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Package Top Marking



XXXXX – Part ID Field: identifies the specific device configuration
 DD – Date Code Field: Coded date of manufacture
 LLL – Lot Code: Designates Lot #
 C – Assembly Site/COO: Specifies Assembly Site/Country of Origin
 RR – Revision Code: Device Revision

Datasheet Revision	Programming Code Number	Locked Status	Part Code	Revision	Date
0.12	002	L	41563	AA	12/22/2016

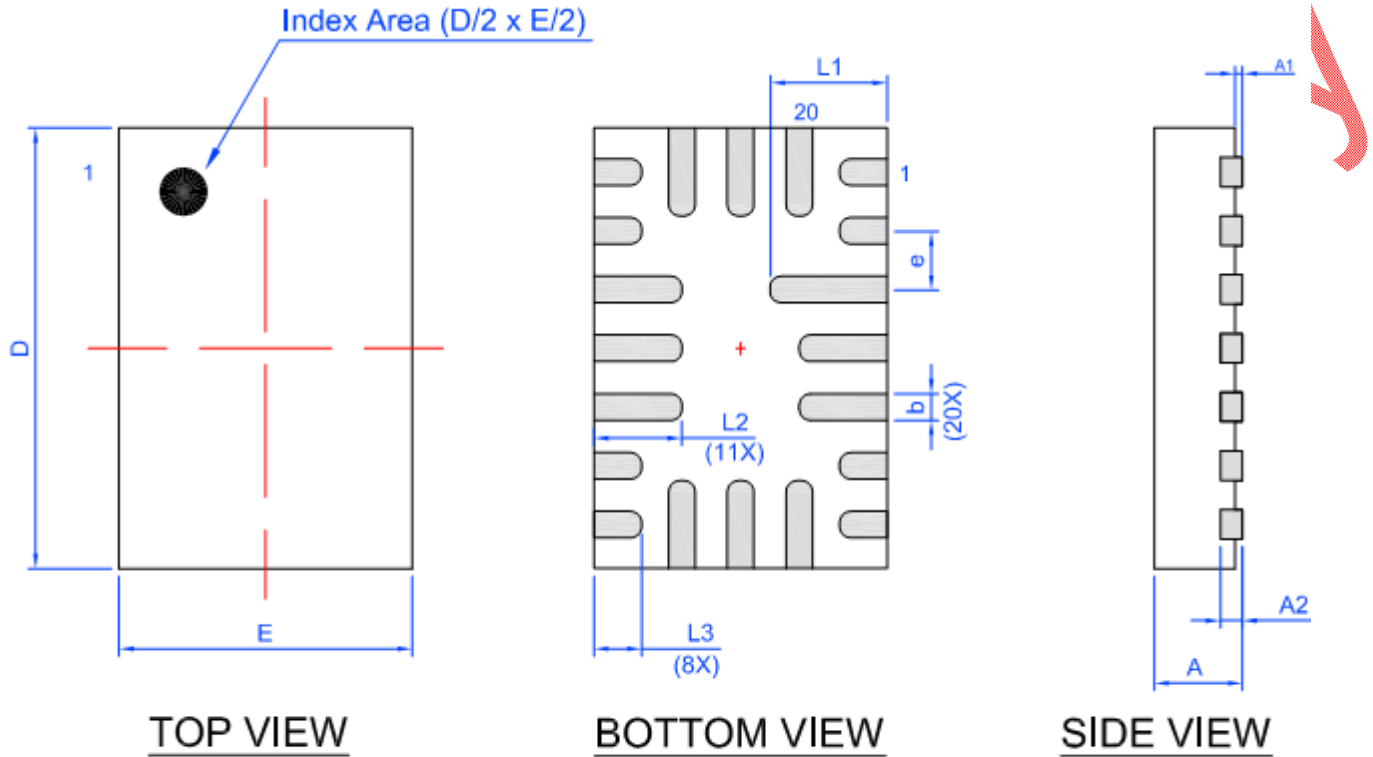
The IC security bit is locked/set for code security for production unless otherwise specified. Revision number is not changed for bit locking.

Internal Use



Package Drawing and Dimensions

20 Lead STQFN Package
 JEDEC MO-220, Variation WECE
 IC Net Weight: 0.0086 g



Unit: mm

Symbol	Min	Nom.	Max	Symbol	Min	Nom.	Max
A	0.50	0.55	0.60	D	2.95	3.00	3.05
A1	0.005	-	0.050	E	1.95	2.00	2.05
A2	0.10	0.15	0.20	L1	0.75	0.80	0.85
b	0.13	0.18	0.23	L2	0.55	0.60	0.65
e	0.40 BSC			L3	0.275	0.325	0.375



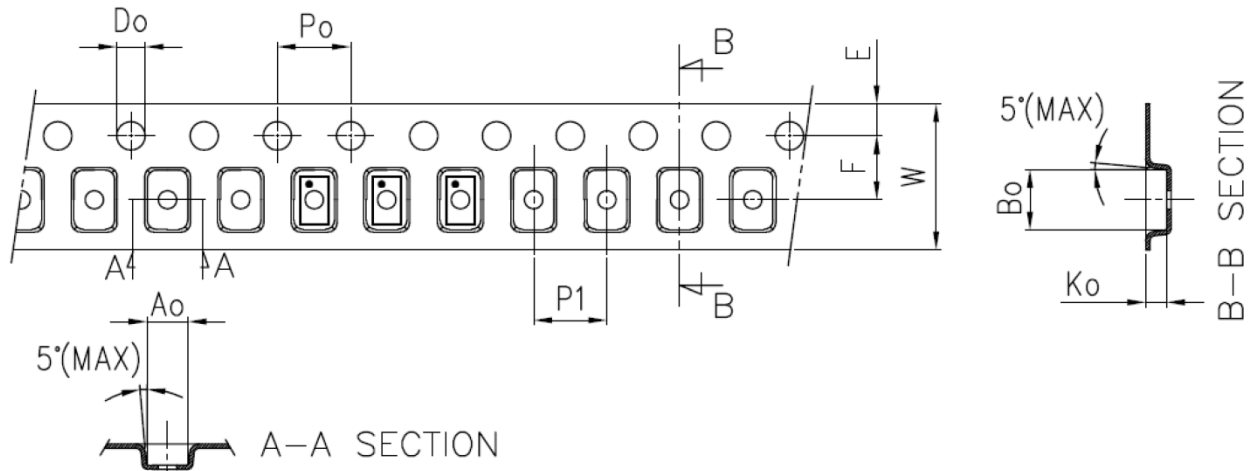
Tape and Reel Specification

Package Type	# of Pins	Nominal Package Size (mm)	Max Units		Reel & Hub Size (mm)	Trailer A		Leader B		Pocket (mm)	
			per reel	per box		Pockets	Length (mm)	Pockets	Length (mm)	Width	Pitch
STQFN 20L 2x3mm 0.4P Green	20	2x3x0.55	3000	3000	178/60	100	400	100	400	8	4

Carrier Tape Drawing and Dimensions

Package Type	Pocket BTM Length (mm)	Pocket BTM Width (mm)	Pocket Depth (mm)	Index Hole Pitch (mm)	Pocket Pitch (mm)	Index Hole Diameter (mm)	Index Hole to Tape Edge (mm)	Index Hole to Pocket Center (mm)	Tape Width (mm)
	A0	B0	K0	P0	P1	D0	E	F	W
STQFN 20L 2x3mm 0.4P Green	2.2	3.15	0.76	4	4	1.5	1.75	3.5	8

Refer to EIA-481 Specifications



Recommended Reflow Soldering Profile

Please see IPC/JEDEC J-STD-020: latest revision for reflow profile based on package volume of 3.3 mm³ (nominal). More information can be found at www.jedec.org.



Datasheet Revision History

Date	Version	Change
12/14/2016	0.10	New design for SLG46722 chip
12/15/2016	0.11	Added PIN15, corrected DLY0 time and PIN14 name
12/22/2016	0.12	Updated Device Revision Summary

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Silego Website & Support

Silego Technology Website

Silego Technology provides online support via our website at <http://www.silego.com/>. This website is used as a means to make files and information easily available to customers.

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GreenCLK1 / GreenCLK2 / GreenCLK3: Crystal replacement technology

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Datasheets and errata, application notes and example designs, user guides, and hardware support documents and the latest software releases are available at the Silego website or can be requested directly at info@silego.com.

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